

ABSTRACT
LAMINATE FOR FLEXIBLE WIRING BOARD

5 A laminate for flexible wiring board in which copper plating is entirely or
locally applied on a copper foil that is cladded on an insulating resin substrate,
characterized in that a ratio $A = [(200)/\{(111) + (200) + (220) + (311)\}] \times 100$, i.e. a
ratio of an area intensity of a peak in the X-ray diffraction of the copper plating
surface is more than 90. The present invention can provide the laminate for
10 flexible wiring board in which copper plating is entirely or locally applied on a copper
foil cladded on an insulating resin substrate, characterized in having particularly
high bendability and enables the formation of fine patterns, namely, high dense
patterns of wiring.

15 Fig. 1